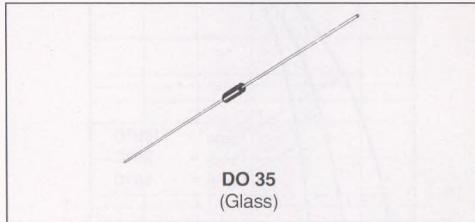


SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching.

Primarily intended for high level UHF/VHF detection and pulse application with broad dynamic range.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	60	V
I_F	Forward Continuous Current*	15	mA
I_{FSM}	Surge non Repetitive Forward Current*	50	mA
T_{stg} T_J	Storage and Junction Temperature Range	- 65 to 200	°C
T_L	Maximum Lead Temperature for Soldering during 10s at 4mm from Case	230	°C

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction-ambient*	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
$V_{(BR)}$	$T_{amb} = 25^\circ C$	$I_R = 10\mu A$	60			V
V_F^{**}	$T_{amb} = 25^\circ C$	$I_F = 1mA$			0.41	V
	$T_{amb} = 25^\circ C$	$I_F = 15mA$			1	
I_R^{**}	$T_{amb} = 25^\circ C$	$V_R = 50V$			0.2	μA

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ C$	$V_R = 0V$	$f = 1MHz$			2.2	pF
τ	$T_{amb} = 25^\circ C$	$I_F = 5mA$	Krakauer Method			100	ps

* On infinite heatsink with 4mm lead length

** Pulse test : $t_b < 300\mu s$ $\delta < 2\%$.

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

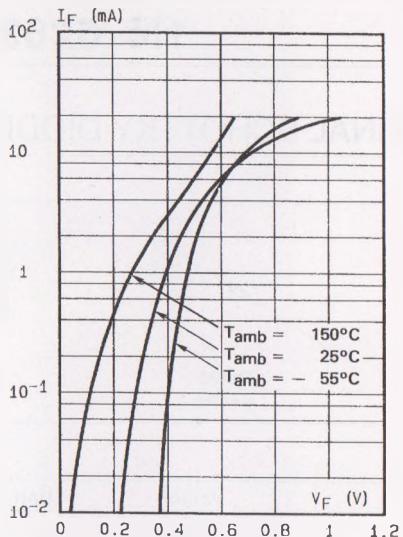


Fig.1 - Forward current versus forward voltage (typical values).

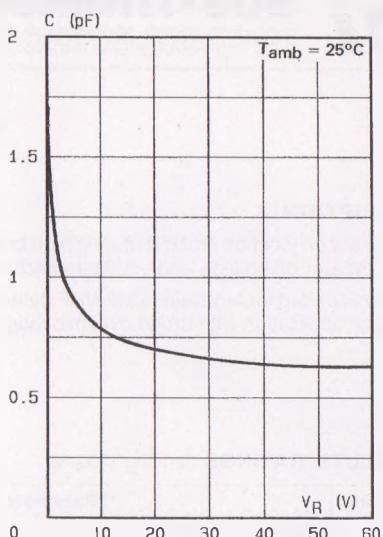


Fig.2 - Capacitance C versus reverse applied voltage V_R (typical values).

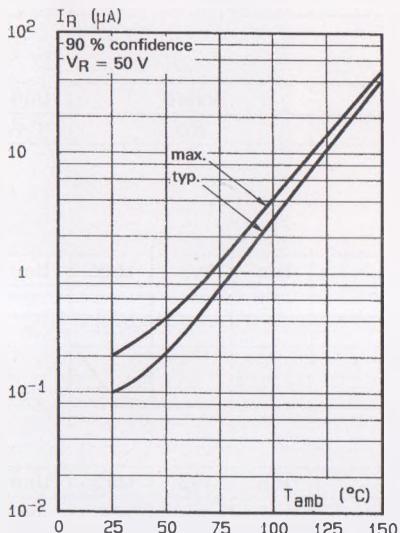


Fig.3 - Reverse current versus ambient temperature.

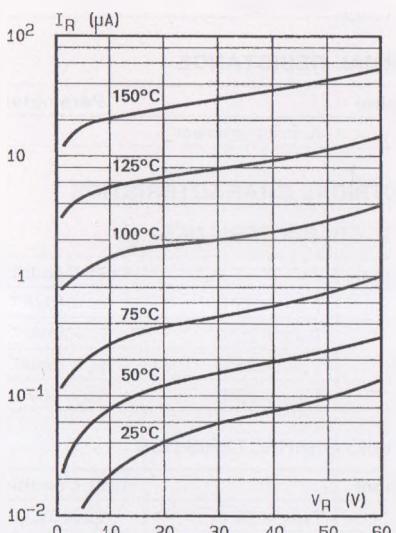


Fig.4 - Reverse current versus continuous reverse voltage (typical values).